

OL-NXH5104UK

wafer level chip-scale package; 13 bumps; 2.74 x 2.80 x 0.38 mm

10 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP13
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	5-10-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.77	-	2.74	2.83	mm
E	package width	2.71	-	2.74	2.77	mm
A	seated height	0.34	-	0.38	0.42	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	13	-	

2. Package outline

Fig. 1. Package outline WLCSP13 (OL-NXH5104UK)



3. Legal information

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